

CALL FOR PAPERS

19th IEEE International Symposium on Embedded Multicore/Many-core Systems-on (McSoC-2026)



Shanghai Jiao Tong University, Shanghai, China • Dec. 14-17, 2026

Heterogeneous Intelligence: Bridging Neuromorphic, Chiplet, Embedded, and Embodied AI Systems



2nd Round Submission Deadline: September 10, 2026 | Notification Date: October 31, 2026 | Camera-Ready & Registration: November 8, 2026

Submit at: <https://edas.info/N34632>

The 19th IEEE International Symposium on Embedded Multicore/Many-core Systems-on-Chip (MCSoc-2026) aims to provide the world's premier forum of leading researchers in the Embedded Multicore/Many-core SoCs software, tools, and applications design areas for academia and industries.

Sponsored by IEEE and the IEEE Computer Society Technical Community on Microprocessors and Microcomputers (TCMM), the 2026 edition will feature a robust technical program including keynote lectures, special sessions, and 19 specialized tracks. Key focus areas include heterogeneous architectures, energy-efficient computing, network-on-chip (NoC) technologies, neuromorphic and brain-inspired systems, and chiplet-based integration.

With past editions hosted in Japan, Austria, France, Italy, South Korea, the United States, China, Singapore, Vietnam, and Malaysia, MCSoc continues to expand its global footprint. The 2026 symposium in Shanghai will build on this legacy, offering a hybrid format to accommodate both in-person and online participation, and reaffirming its role as a driving force in shaping the future of intelligent multicore systems.

Prospective authors are invited to submit their contributions. Submission of a contribution implies that at least one of the authors will have full registration to the symposium upon acceptance of their contribution. Submissions can include technical, experimental, theoretical, conceptual, or a survey.

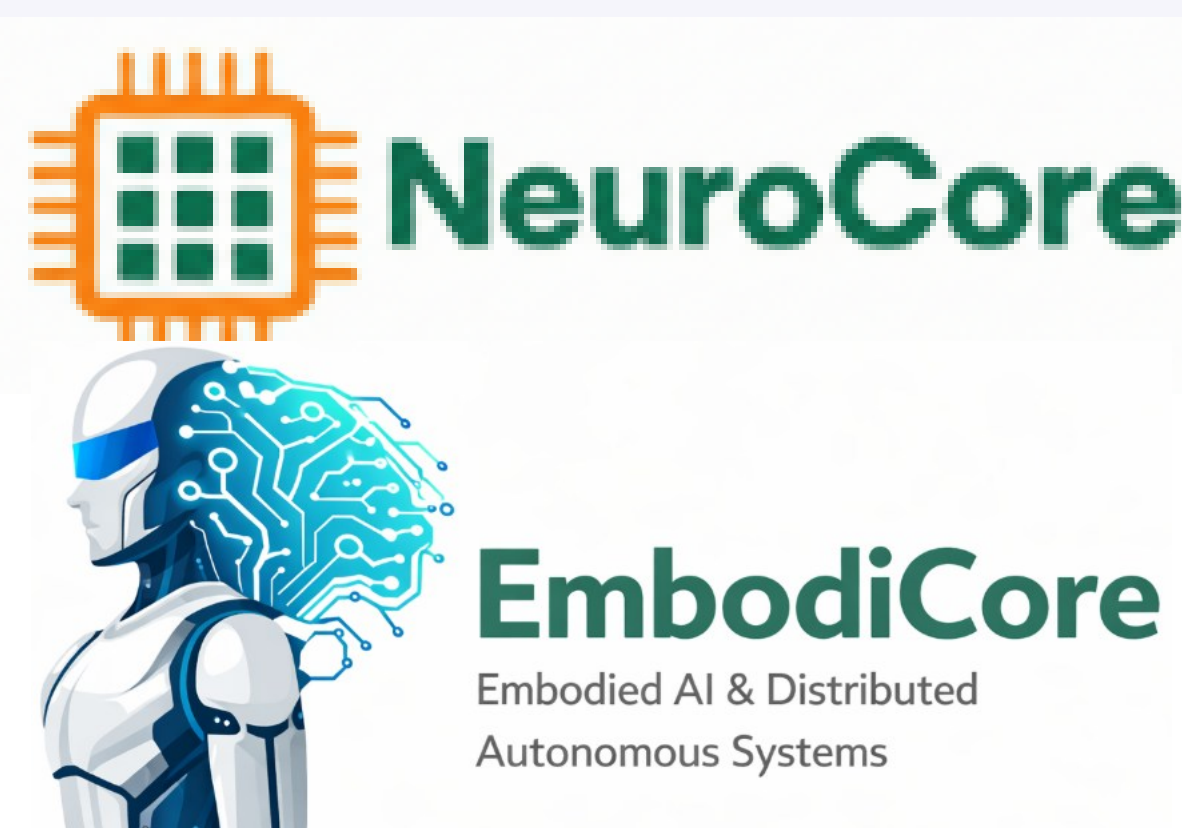
****The conference is a hybrid event****

Technical Tracks

- Programming Techniques for Embedded Multicore/Manycore SoCs
- Architectural Innovations in Embedded Multicore/Manycore SoCs
- Design Methodologies for Embedded Multicore/Manycore SoCs
- Heterogeneous Integration and Advanced On-Chip Interconnects
- Testing, Security, and Trust in Embedded Multicore/Manycore Systems
- Design Automation and Low-Power Techniques for Embedded Manycore SoCs
- Real-Time Systems for Embedded Multicore/Manycore SoCs
- Operating System Platforms for Real-Time Embedded Applications
- Hardware Acceleration of AI on Embedded Edge SoCs
- Machine Learning for Energy-Efficient and Reliable Manycore Systems
- Chiplet-Based Architectures and Design for Multicore SoCs
- Sustainable Design and Lifecycle Management for Multicore SoCs
- Privacy-Preserving AI Acceleration on Embedded Multicore SoCs
- Multicore SoCs for Cyber-Physical and Autonomous Systems
- Application Domains for Embedded Multicore/Manycore SoCs
- Quantum and Hybrid Classical-Quantum Computing SoCs

MCSoc Global Summits

- 2026 MCSoc-NeuroCore Global Summit on Neuromorphic Systems and Brain-Inspired Computing
- 2026 MCSoc-EmbodiCore Global Summit on Embodied AI and Distributed Autonomous Systems



Special Sessions

- Performance Optimization and Auto-Tuning (POAT2026)
- Embedded, Cyber-Physical, and IoT Systems
- Human-Centric AI & Intelligent Systems for Sustainable Industry
- Quantum Technology and Machine Learning
- Intelligent Systems and Learning Technologies

Proceedings Publication and Indexing

The conference proceedings, including all technical tracks, special tracks, and special sessions and workshop papers, will be published by IEEE Conference Proceedings, which will be included in the Computer Society Digital Library CSDL and IEEE Xplore. All CPS conference publications are also submitted for indexing to EI's Engineering Information Index, Compendex, ISI Thomson's Scientific and Tech. Pro. Scopus, ISTP/ISI Proceedings.

More Information

<https://www.mcsoc-forum.org/>

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- Hideharu Amano, Prefectural University of Kumamoto

Conference Co-Chairs

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- Amirreza Yousefzadeh, University of Twente
- Fawaz Alazemi, Kuwait University

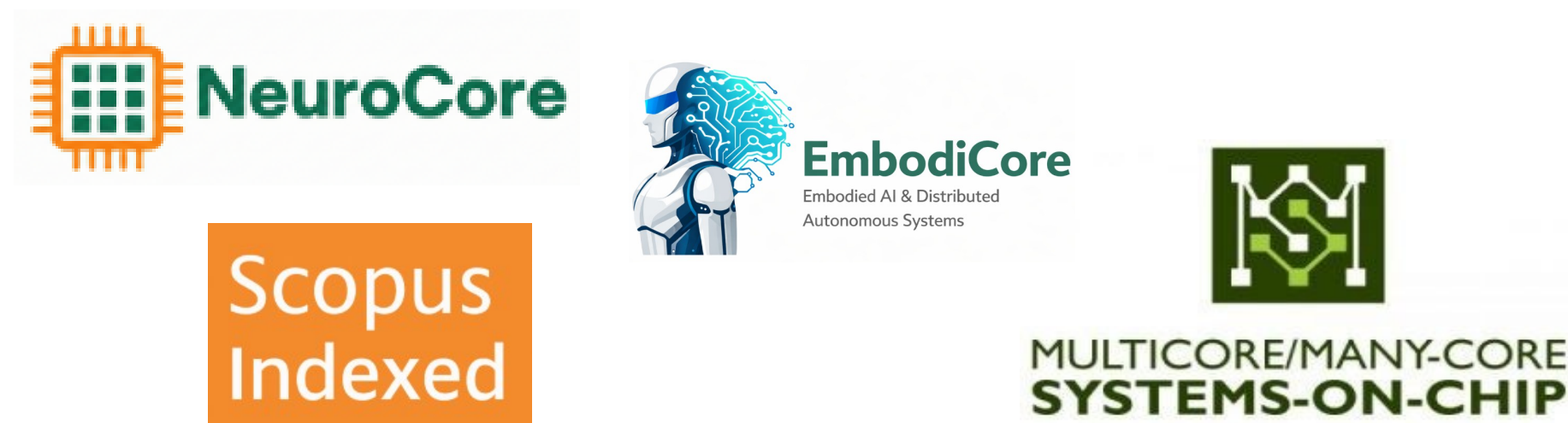
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